Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.016”**



**E**

**B**

**.020”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .003” X .004”**

**Backside Potential: Collector**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .016” X .020” DATE: 9/7/21**

**MFG: MOTOROLA THICKNESS .006” P/N: 2N2484**

**DG 10.1.2**

#### Rev B, 7/19/02